

55358-5021	55358-50**
MATERIAL No.	MODEL No.

<b>REVISED</b> EC NO: J2009-0469 DRWN: YOSHIDAM 2008/12/01 CHKD: THARUYAMA 2008/12/01 APPR: NUKITA 2008/12/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE <b>2:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	±0.25	T. HIRAYAMA	'98/09/01	<b>CF CARD CONN.          50P HEADER ASSY          (TYPE I/II,NORMAL)</b>		
	30 OVER	±0.3	M. SASAO	'98/09/01			
ANGULAR	±3 °	APPROVED BY	DATE	<b>MOLEX INCORPORATED</b>			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		H. IKESUGI	'98/09/01	DOCUMENT NO. <b>SD-55358-003</b>		SHEET NO.	1 OF 2
		MATERIAL NO. <b>SEE TABLE</b>		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注) 1. 材質  
NOTES MATERIAL

ハウジング : ガラス入りLCP UL94V-0  
HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0  
ピン : リン青銅  
PIN: PHOSPHOR BRONZE  
ネール : リン青銅 (t0.3)  
NAIL: PHOSPHOR BRONZE (t0.3)  
リヤネール : リン青銅 (t0.48)  
REAR-NAIL: PHOSPHOR BRONZE (t0.48)

2. ヌッキ仕様  
PLATING

ピン 接点部 : パラジウムニッケル下地、金メッキ  
CONTACT AREA: GOLD OVER PALLADIUM-NICKEL  
半田付け部 : 半田メッキ  
SOLDER TAIL AREA: TIN-LEAD  
下地メッキ : ニッケルメッキ  
UNDERPLATING: NICKEL OVER ALL  
ネール 接点部 : 金メッキ  
NAIL CONTACT AREA: GOLD  
半田付け部 : 半田メッキ  
SOLDER TAIL AREA: TIN-LEAD  
下地メッキ : ニッケルメッキ  
UNDERPLATING: NICKEL OVER ALL  
リヤネール 半田メッキ  
REAR-NAIL TIN-LEAD  
下地メッキ : 銅メッキ  
UNDERPLATING: COPPER OVER ALL

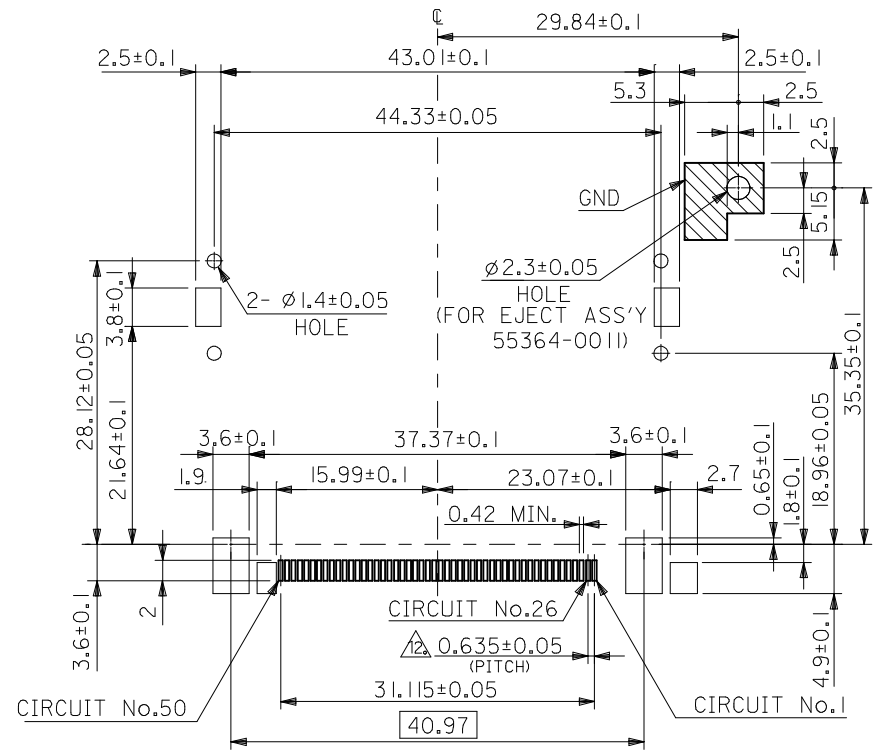
3. 推奨基板厚 : t=0.8 MIN.  
RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.  
4. 適合カード厚 : 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)  
RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)

5. 適合カード幅 : 42.8±0.1  
RECOMMENDED CARD WIDTH: 42.8±0.1

6. ハウジング色 : 黒  
HOUSING COLOR: BLACK

- △ 寸法適用極 : 1,13,38,50  
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
- △ 寸法適用極 : 25,26  
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
- △ ピンの倒れは、ピン根元を基準に全方向へ 0.1 MAX.とする。  
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
- △ ピン根元に適用する。  
THIS DIMENSION TO BE MEASURED AT PIN BASE.

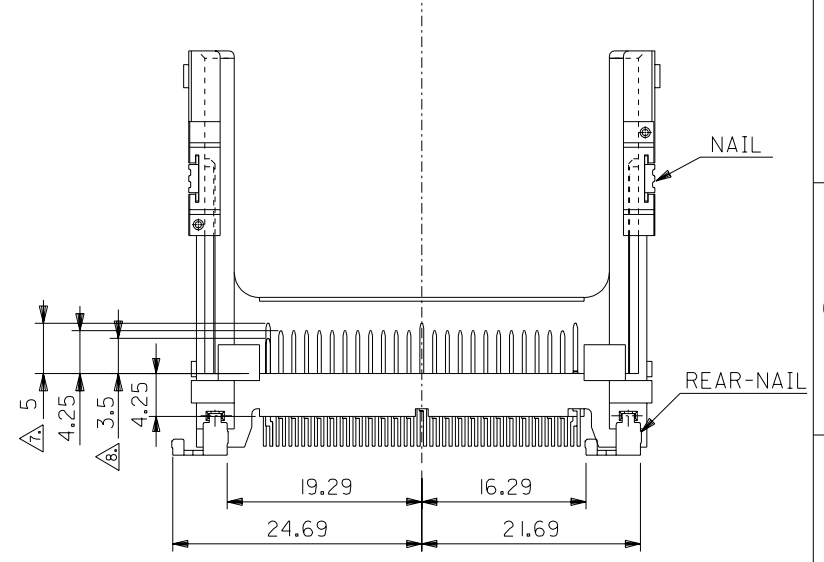
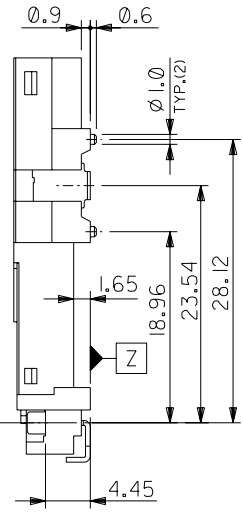
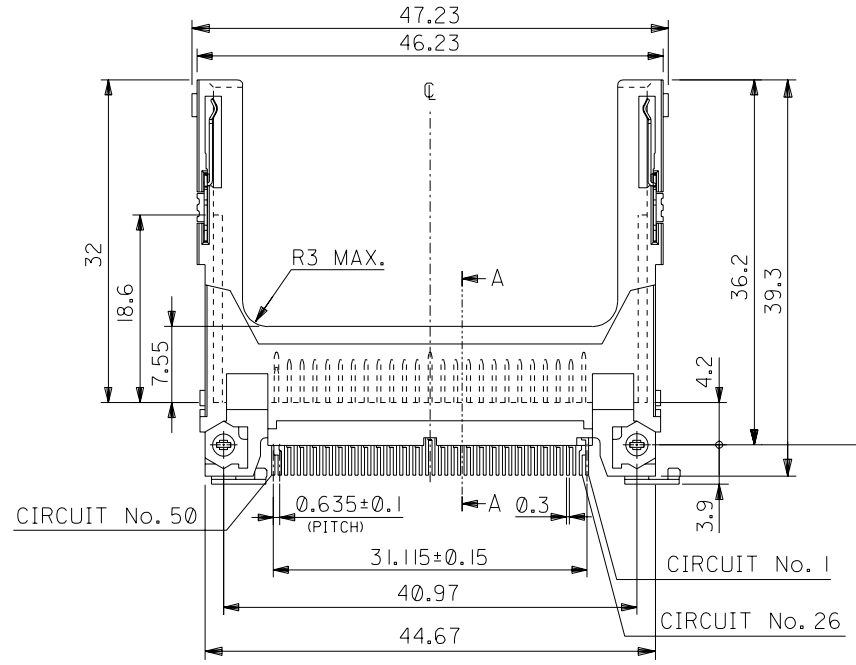
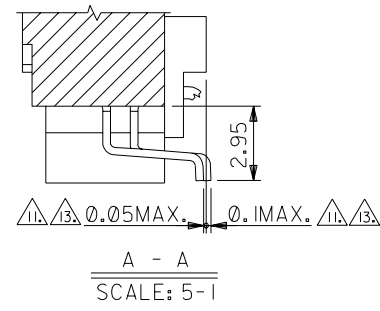
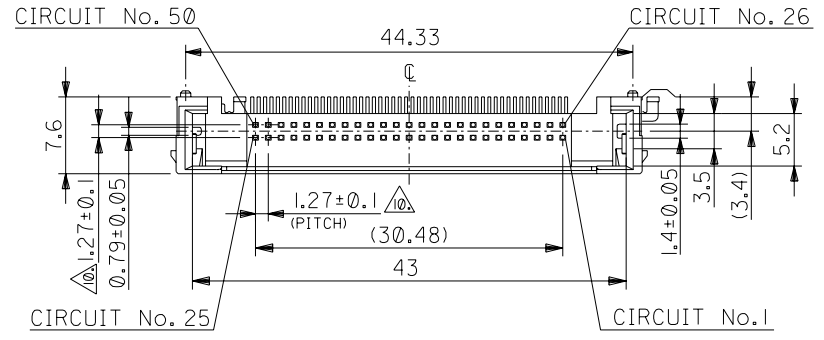
- △ ソルダータールは、Z面を基準とし上へ 0.05 下へ 0.1の範囲にあり、且つソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。  
SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDERTAILS TO BE WITHIN 0.1.  
MEASUREMENT POINT IS SOLDERTAILS TIP.
- △ 公差非累積  
NON-CUMULATIVE
- △ テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。  
TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.



基板推奨寸法  
RECOMMENDED P.C.B. LAYOUT

REVISED EC NO: J2009-0469 DRWN: YOSHIDAM 2008/12/01 CHKD: THARUYAMA 2008/12/01 APPR: NUKITA 2008/12/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. HIRAYAMA	DATE '98/09/01	TITLE CF CARD CONN. 50P HEADER ASSY (TYPE I/II,NORMAL)	
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '98/09/01	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE '98/09/01	MATERIAL NO. SEE SHEET1	DOCUMENT NO. SD-55358-003
REV	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

DWG. NO. SD-55358-011



DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:
RELEASED				
EC NO. J2002-3139				
DRWN: THANYU '02/06/17				
CHK: MSASAO '02/06/17				
APPR: MSASAO '02/06/17				

MATERIAL 材料	SEE NOTES
FINISH 仕上り	SEE NOTES
WIRE RANGE 適用電線範囲	—
INS. RANGE 被覆外径	—

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	10 UNDER 未満	±0.2
	10 OVER 30 UNDER 以上 未満	±0.25
	30 OVER 以上	±0.3
ANGLE 角度		±3°

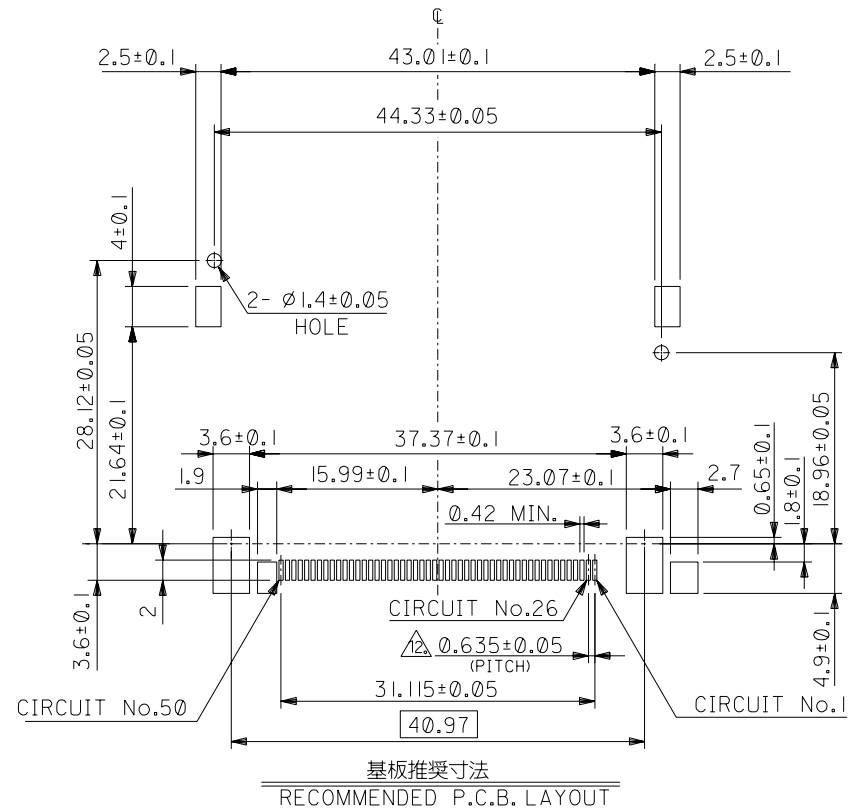
SCALE 2 - 1	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH
DRAWN BY & DATE T. Hamura '02/06/17	
CHECKED BY & DATE H. Sasaki '02/06/17	
APPROVED BY & DATE H. Sasaki '02/06/17	
CAD FILENAME SD-55358-011.S01	

55358-5021		55358-50**	
MATERIAL No.		MODEL No.	
DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH		SHT REV REVISE ON CAD ONLY	
THIRD ANGLE PROJECTION			
TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL)			
MOLEX INCORPORATED			
MATERIAL NO. SEE CHART	DRAWING NO. SD-55358-011	SHEET NO. 1 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			SIZE B

DWG. NO. SD-55358-011

- 8 7 6 5 4 3 2 1
- 注) 1. 材質 MATERIAL  
 ハウジング: ガラス入りLCP UL94V-0  
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0  
 ピン: リン青銅  
 PIN: PHOSPHOR BRONZE  
 ネール: リン青銅 (t0.3)  
 NAIL: PHOSPHOR BRONZE (t0.3)  
 リヤネール: リン青銅 (t0.48)  
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING  
 ピン PIN 接点部: パラジウムニッケル下地、金メッキ  
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL  
 半田付け部: 半田メッキ  
 SOLDER TAIL AREA: TIN-LEAD  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL  
 ネール NAIL 接点部: 金メッキ  
 CONTACT AREA: GOLD  
 半田付け部: 半田メッキ  
 SOLDER TAIL AREA: TIN-LEAD  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL  
 リヤネール REAR-NAIL 半田メッキ  
 TIN-LEAD  
 下地メッキ: 銅メッキ  
 UNDERPLATING: COPPER OVER ALL
3. 推奨基板厚: t=0.8 MIN.  
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)  
 RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅: 42.8±0.1  
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒  
 HOUSING COLOR: BLACK
7. 寸法適用極: 1, 13, 38, 50  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1, 13, 38 AND 50.
8. 寸法適用極: 25, 26  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
9. ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。  
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
10. ピン根元に適用する。  
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

11. ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且ツソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。  
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
12. 公差非累積  
 NON-CUMULATIVE
13. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。  
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.



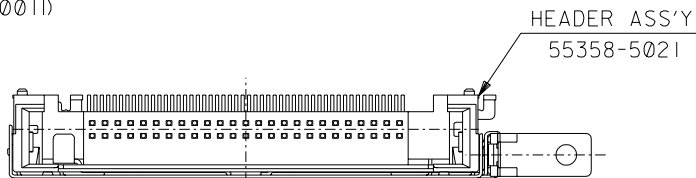
基板推奨寸法  
 RECOMMENDED P.C.B. LAYOUT

DO NOT SCALE DRAWING

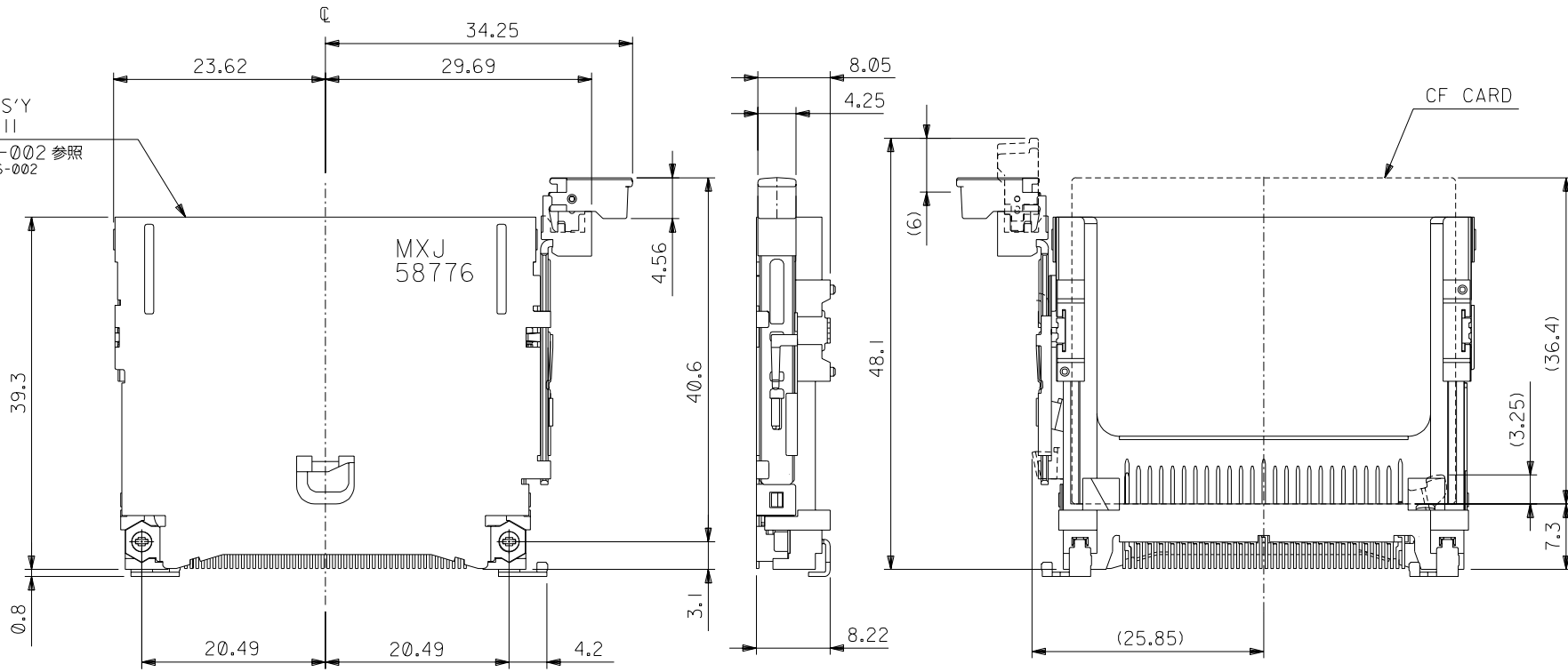
EC NO. DRAWN: CHK: APPR:	EC NO. DRAWN: CHK: APPR:	EC NO. DRAWN: CHK: APPR:	EC NO. DRAWN: CHK: APPR:	EC NO. DRAWN: CHK: APPR:	REV	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT	REV	
						SEE NOTES	10 UNDER 未滿	±0.2	2 - 1	mm INCH	◎	mm ONLY		
						FINISH 仕上げ	10 OVER 以上	±0.25						
						SEE NOTES	30 UNDER 未滿	±0.3						
						WIRE RANGE 適用電線範囲	ANGLE 角度	±3°						
						INS. RANGE 被覆外径								
TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL)														
MOLEX INCORPORATED														
CAD FILENAME SD-55358-011.S02								MATERIAL NO. —		DRAWING NO. SD-55358-011		SHEET NO. 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.											SIZE B			

REFERENCE USE ONLY

NORMAL MOUNT TYPE  
(55358-5021 & 55356-0011)



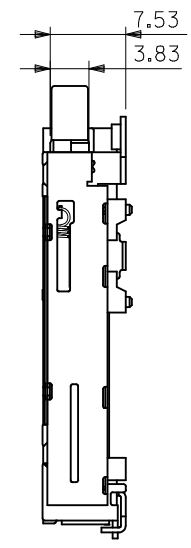
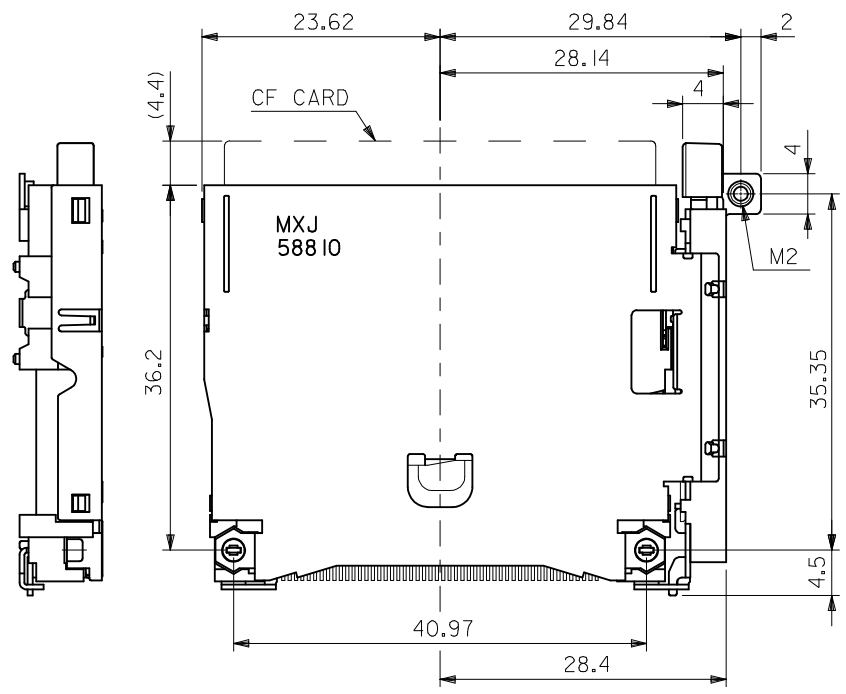
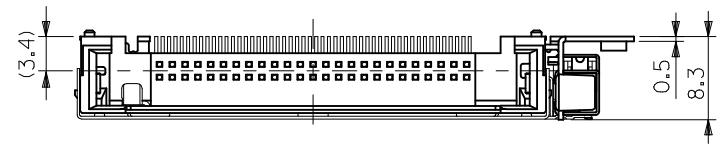
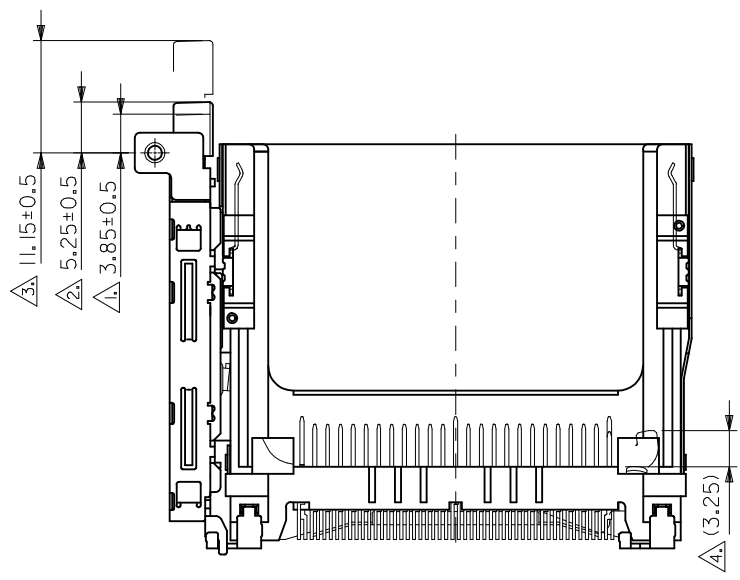
SHELL ASS'Y  
55356-0011  
SD-55356-002 参照  
SEE SD-55356-002



DO NOT SCALE DRAWING

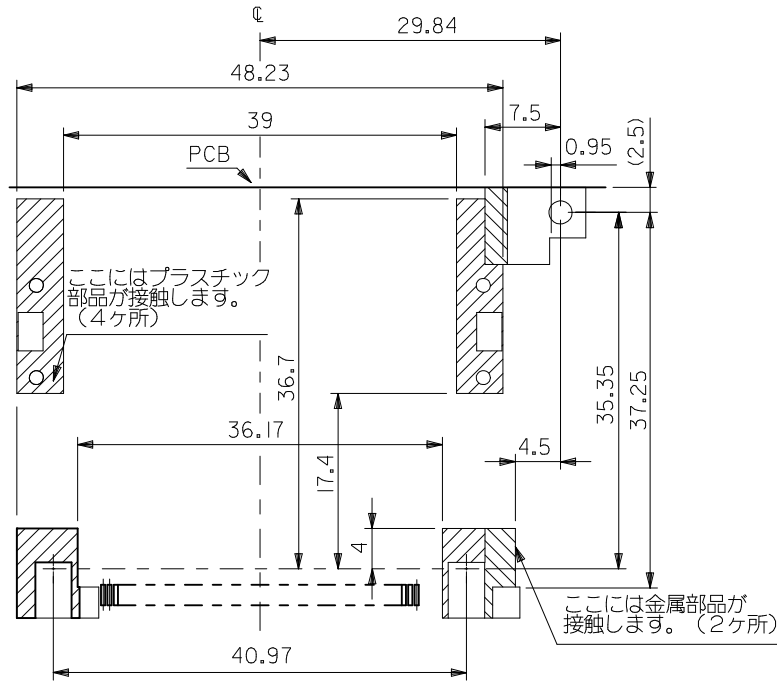
EC NO. DRWN: CHK: APPR:				EC NO. DRWN: CHK: APPR:				EC NO. DRWN: CHK: APPR:				EC NO. DRWN: CHK: APPR:				SEE SHEET 1 OF 3 EC NO. DRWN: CHK: APPR:				MATERIAL 材料				GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差				SCALE 2 - 1				DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH				THIRD ANGLE PROJECTION				DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY				SHT REV											
FINISH 仕上り				WIRE RANGE 適用電線範囲				INS. RANGE 被覆外径				10 UNDER 未満				10 OVER 30 UNDER 以上 未満				30 OVER 以上				ANGLE 角度				DRAWN BY & DATE T. Hamura '02/06/17				CHECKED BY & DATE H. Sato '02/06/17				APPROVED BY & DATE [Signature] '02/06/17				CAD FILENAME SD-55358-011.S03				MATERIAL NO. #				DRAWING NO. SD-55358-011				SHEET NO. 3			
TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II,NORMAL)																								MOLEX INCORPORATED				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B																							

- 注) NOTES
- 1. ボタン・フルストローク位置。  
BUTTON'S FULL STROKE POSITION.
  - 2. ボタン収納時位置。  
BUTTON'S IN POSITION.
  - 3. ボタン突出時位置。  
BUTTON'S OUT POSITION.
  - 4. イジェクト時、カード飛び出し量は(3.25)mm。  
IN EJECTING OPERATION, CARD OUT BY (3.25)mm.

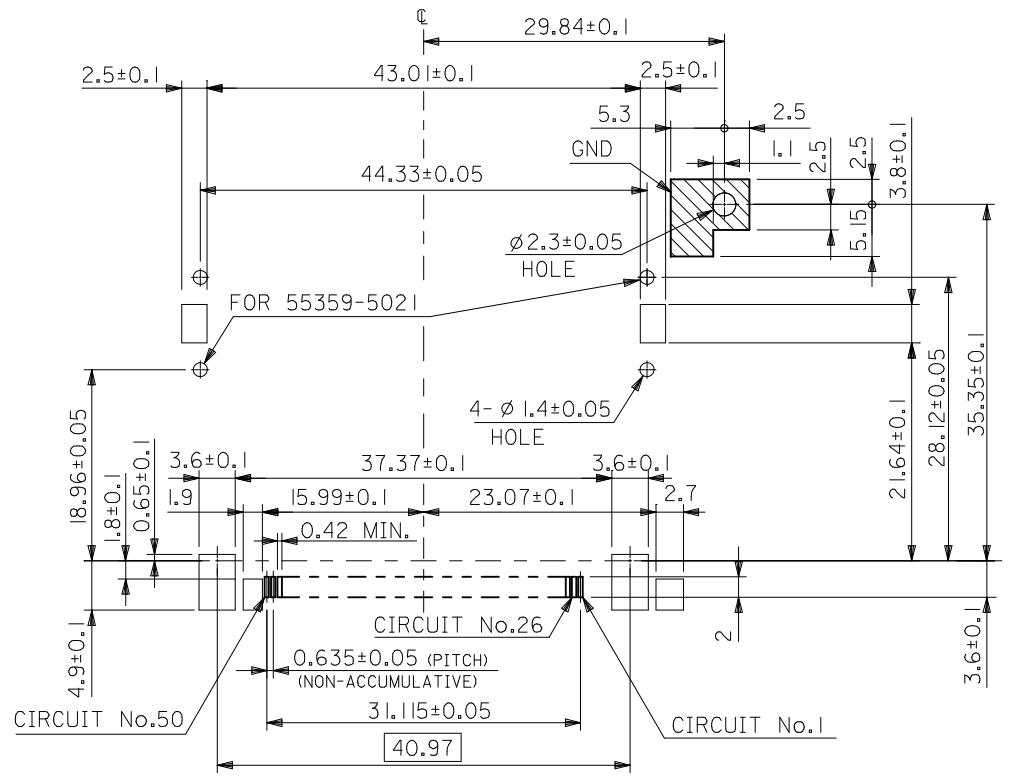


EJECT ASS'Y	55364-0011
MATERIAL No.	

REVISED EC NO.: J2014-0509 DRWN: YSEDA 2013/09/19 CHKD: ASHIMOTSU 2013/09/19 APPR: NUKITA 2013/10/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>	SCALE <b>2:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION	
	10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	DRAWN BY THIRATA	DATE 1998/09/08	TITLE <b>CF CARD CONN.          EJECT MECHANISM          (TYPE I/II NORMAL)</b>	
	ANGULAR ±3 °			CHECKED BY MSASAO	DATE 1998/09/08	<b>molex</b>	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			APPROVED BY HIKESUGI	DATE 1998/09/08	DOCUMENT NO. <b>SD-55364-003</b>	SHEET NO. <b>1 OF 3</b>
REV D	DESCRIPTION	SEE TABLE	MATERIAL NO. THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



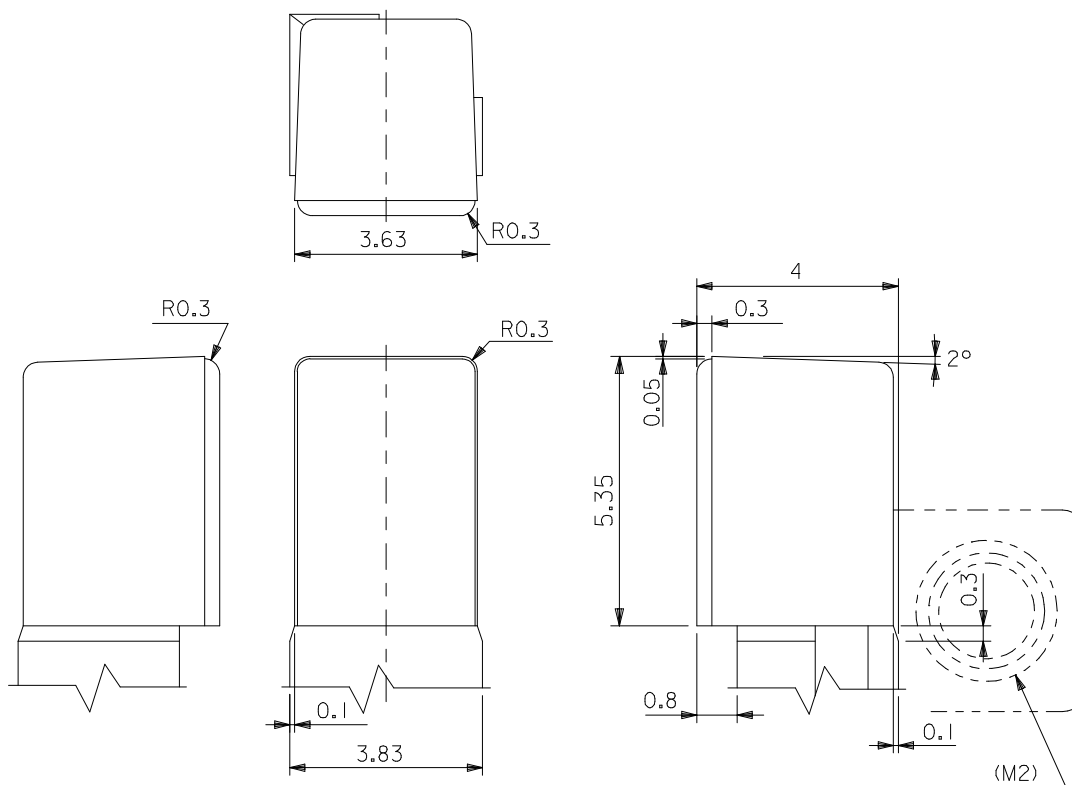
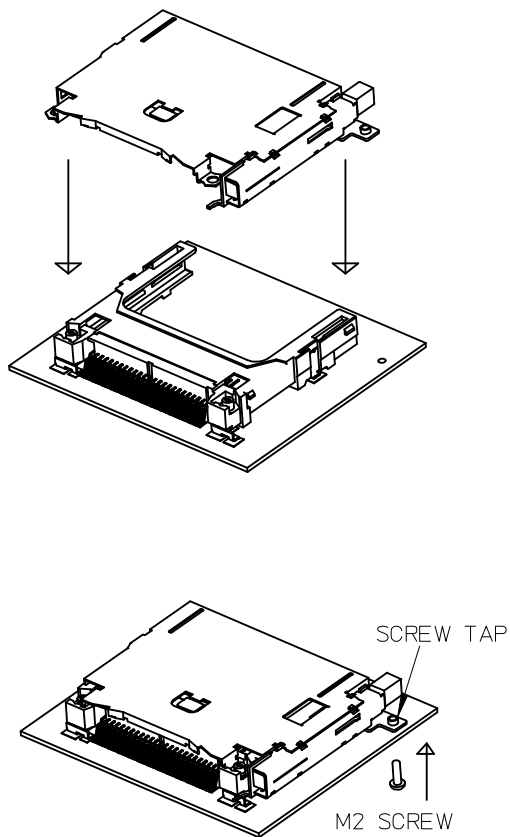
この図はすべて絶対寸法です。



基板推奨寸法  
RECOMMENDED P.C.B. LAYOUT

REVISED EC NO: J2014-0509 DRWN:YSENA 2013/09/19 CHK:DASHIMOTSU 2013/09/19 APPR:NUKITA 2013/10/01 D	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION CF CARD CONN. EJECT MECHANISM (TYPE I/II NORMAL) <b>molex</b> SEE SHEET 1 SD-55364-003 2 OF 3
		DRAWN BY THIRATA DATE 1998/09/08		TITLE		
		CHECKED BY MSASAO DATE 1998/09/08		MATERIAL NO.		
		APPROVED BY HIKESUGI DATE 1998/09/08		DOCUMENT NO.		
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

# MOUNTING METHOD



ボタン詳細寸法  
DETAIL OF BUTTON

REVISED EC NO: J2014-0509 DRWN:YSEDA 2013/09/19 CHKD:ASHIMOTSU 2013/09/19 APPR:NUKITA 2013/10/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY THIRATA	DATE 1998/09/08	CF CARD CONN. EJECT MECHANISM (TYPE I/II NORMAL)	
	10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 1998/09/08		
	30 OVER	±0.3	APPROVED BY HIKESUGI	DATE 1998/09/08		
ANGULAR	±3 °	MATERIAL NO. SEE SHEET1		DOCUMENT NO. SD-55364-003	SHEET NO. 3 OF 3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				